

ON Semiconductor					10/15/2019
Base Part		FSL128MRT	HF		
Orderable Part		FSL128MRTWDTU	Total weight (mg)	2239.005	
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight	
Die	9.8	Silicon (Si)	7440-21-3	100	
Die Attach Epoxy	0.254	Silver (Ag)	7440-22-4	85	
		Phenolic Resin-2	54208-63-8	15	
Die Attach Solder	3.061	Silver (Ag)	7440-22-4	2.5	
		Lead (Pb)	7439-92-1	92.5	
		Tin (Sn)	7440-31-5	5	
Lead Frame	1264.586	Silver (Ag)	7440-22-4	0.23011484	
		Tin (Sn)	7440-31-5	0.12256976	
		Copper (Cu)	7440-50-8	99.63735167	
		Phosphorus (P)	7723-14-0	0.00996374	
Mold Compound-Black	950	Ortho Cresol Novolac Resin	29690-82-2	12	
		Carbon Black (C)	1333-86-4	0.5	
		Fused Silica (SiO2)	60676-86-0	87.5	
Plating	11	Tin (Sn)	7440-31-5	100	
Wire Bond - Cu	0.304	Copper (Cu)	7440-50-8	100	
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>					